

2017 Global and Regional Wire Bonder Equipment Market Research Report Forecasts 2022

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Abstracts

This report focus on Global and regional market, providing information on major players like manufacturers, suppliers, distributors, traders, customers, investors and etc., major types, major applications from Global and major regions such as Europe, North American, South American, Asia (Excluding China), China and etc. Data type include capacity, production, market share, price, revenue, cost, gross, gross margin, growth rate, consumption, import, export and etc. Industry chain, manufacturing process, cost structure, marketing channel are also analyzed in this report.

This report provides valuable information for companies like manufacturers, suppliers, distributors, traders, customers, investors and individuals who have interests in this industry.

Major companies are as follows:

ASM Pacific Technology, Kulicke and Soffa Industries, Applied Materials, Palomar Technologies, BE Semiconductor Industries, FandK Delvotec Bondtechnik GmbH, DIAS Automation, West Bond, Hesse Mechatronics, HYBOND; Inc,

Major types are as follows:

Wedge Bonders, Stud-Bump Bonders, Ball Bonders

Major applications are as follows:

Integrated Device Manufacturer (IDMs), Outsourced Semiconductor Assembly and Testing (OSATs),

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